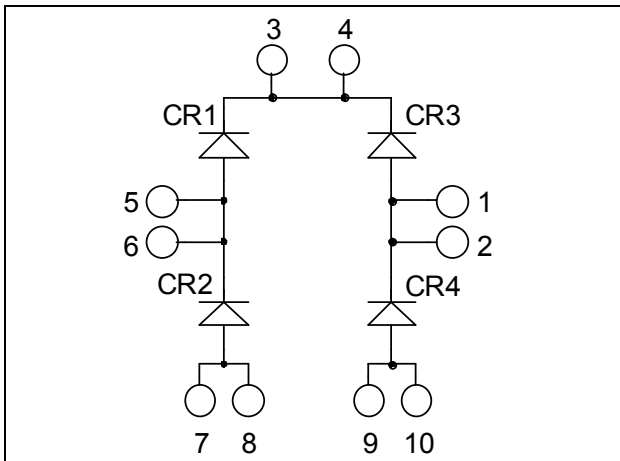


## Fast Diode Full Bridge Power Module

$V_{RRM} = 600V$   
 $I_C = 30A @ T_c = 90^\circ C$

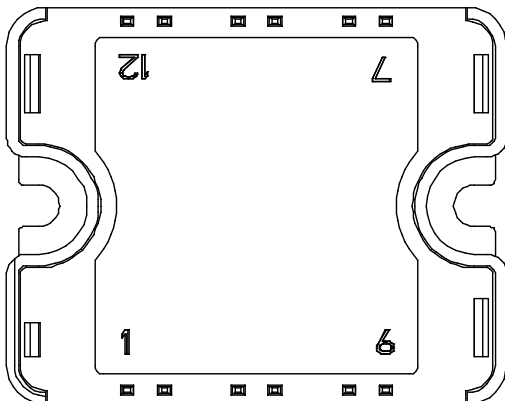


### Application

- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

### Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
- High level of integration



### Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

All multiple inputs and outputs must be shorted together  
 3/4 ; 5/6 ; 7/8 ; 1/2 ; 9/10

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit	
$V_R$	Maximum DC reverse Voltage	600	V	
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage			
$I_{F(AV)}$	Maximum Average Forward Current	Duty cycle = 50%	A	
		$T_C = 25^\circ C$		42
		$T_C = 90^\circ C$	30	
$I_{FSM}$	Non-Repetitive Forward Surge Current	8.3ms	$T_J = 45^\circ C$	250

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$V_F$	Diode Forward Voltage	$I_F = 30\text{A}$		1.8	2.2	V
		$I_F = 60\text{A}$		2.2		
		$I_F = 30\text{A}$	$T_j = 125^\circ\text{C}$	1.5		
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 600\text{V}$	$T_j = 25^\circ\text{C}$		250	$\mu\text{A}$
			$T_j = 125^\circ\text{C}$		500	
$C_T$	Junction Capacitance	$V_R = 200\text{V}$		36		pF

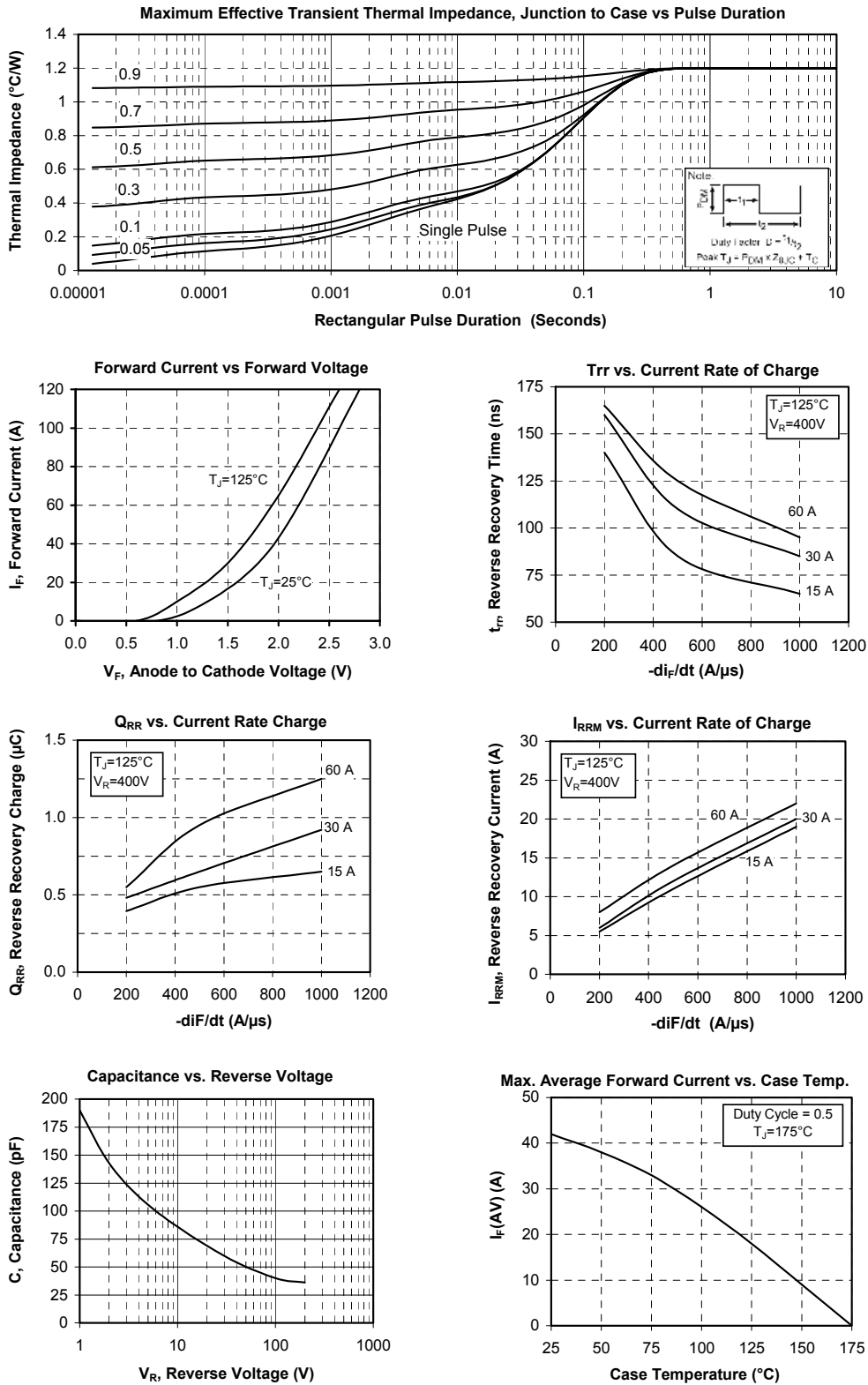
**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$t_{rr}$	Reverse Recovery Time	$I_F = 30\text{A}$ $V_R = 400\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		25	ns
			$T_j = 125^\circ\text{C}$		160	
$Q_{rr}$	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$		35	nC
			$T_j = 125^\circ\text{C}$		480	
$I_{RRM}$	Reverse Recovery Current		$T_j = 25^\circ\text{C}$		3	A
			$T_j = 125^\circ\text{C}$		6	
$t_{rr}$	Reverse Recovery Time	$I_F = 30\text{A}$ $V_R = 400\text{V}$ $di/dt = 1000\text{A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		85	ns
$Q_{rr}$	Reverse Recovery Charge				920	nC
$I_{RRM}$	Reverse Recovery Current				20	A

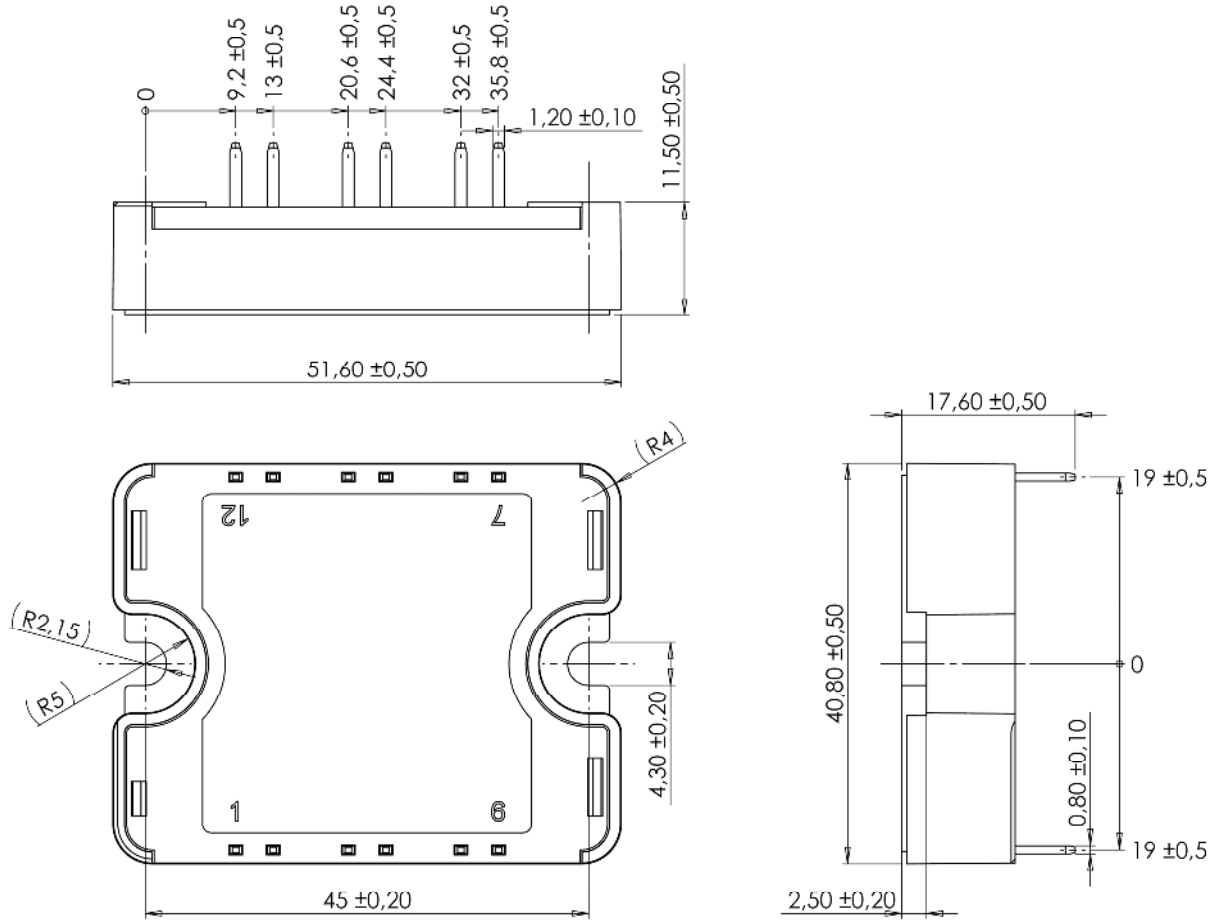
**Thermal and package characteristics**

Symbol	Characteristic	Min	Typ	Max	Unit	
$R_{thJC}$	Junction to Case Thermal Resistance			1.2	$^\circ\text{C}/\text{W}$	
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}$ , 50/60Hz	4000			V	
$T_j$	Operating junction temperature range	-40		175	$^\circ\text{C}$	
$T_{STG}$	Storage Temperature Range	-40		125		
$T_C$	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight				80	g

## Typical Performance Curve



**SP1 Package outline** (dimensions in mm)



See application note 1904 - Mounting Instructions for SP1 Power Modules on [www.microsemi.com](http://www.microsemi.com)

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